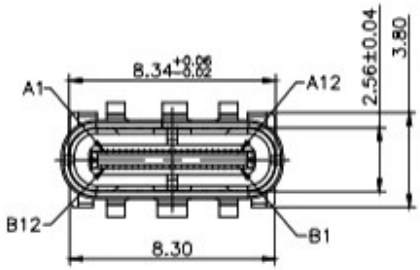
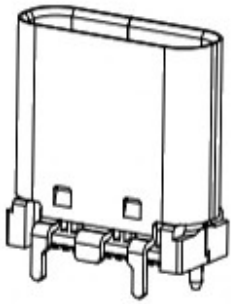
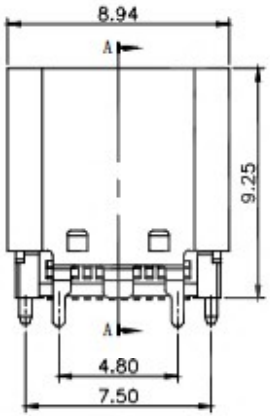
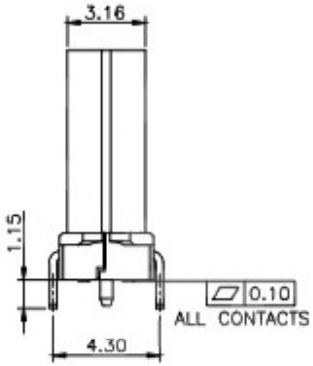
REV	ECN No.	DATE	REMARK
A	NEW	2016.08.22	新版发行
B	ECN1611015	2016.11.30	铁壳脚尺寸0.05==>0.10$^{0.10}_{0.05}$
C	ECN1612001	2016.12.23	变更新料号
D	ECN1805012	2018.05.29	镀金1u ==> 3u
E	ECN190415001	2019.04.16	修改图纸摆放方式

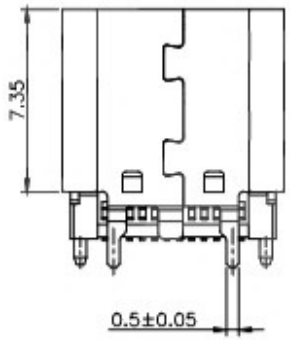
RoHS Compliant Pb

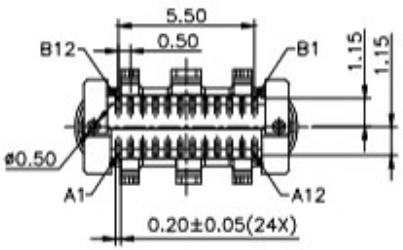


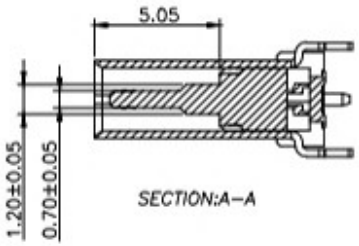












NOTE:

1.MATERIAL SPECIFICATION:
- 1.HOUSING:HIGH TEMPERATURE RESISTANT PLASTIC(LCP),UL94 V-0.
- 2.CONTACTS:COPPER ALLOY(C1814)T=0.12mm
- 3.MID PLATE: STAINLESS STEEL(SUS301)T=0.20mm
- 4.EMI PLATE: STAINLESS STEEL(SUS301)T=0.10mm
- 5.SHELL: STAINLESS STEEL(SUS304)T=0.30mm

2.PLATING SPECIFICATION:

2-1.CONTACTS:
Ni 50u" MIN. UNDER PLATED OVER ALL.
Au PLATED ON THE FUNCTIONAL AREA OF CONTACT.
(GOLD PLATING THICKNESS FOLLOW THE P/N)
PLATING SPECIFICATIONS OF THE SOLDER AREA FOLLOW THE P/N

2-2.FRONT SHELL&OUTER SHELL:
Ni 30u" MIN. UNDER PLATED OVER ALL.

2-3.MID PLATE:
Ni 30u" MIN. UNDER PLATED OVER ALL.
Sn 80u"MIN. PLATED OVER ALL

2-4.EMI PLATE:
CLEAR ONLY

3.MECHANICAL PERFORMANCE.
- 3-1.INSERTION FORCE: 0.5~2.0kgf.
- 3-2.REMOVAL FORCE: 0.8kgf~2.0kgf.
- 3-3.DURABILITY: 10000 CYCLES.

4.ELECTRICAL PERFORMANCE.
- 4-1. CURRENT RATING:5.0A
  VOLTAGE RATING:5.0V
- 4-2. LLCR:
  VBUS & GND PINS AND OTHER PINS: 40mΩ/PIN MAX.
  SHIELD: 50mΩ/MAX.
  LLCR MAX. CHANGE OF ALL PINS: 10mΩ.
- 4-3.INSULATION RESISTANCE: 100MΩ MIN
- 4-4.DIELECTRIC WITHSTAND VOLTAGE,AC 100V FOR 1 MINUTE.

5. ENVIRONMENTAL PERFORMANCE:
OPERATING TEMPERATURE: -25°C~+85°C.

6.IR REFLOW:
THE PEAK TEMPERATURE ON THE BOARD SHALL BE MAINTAINED FOR 10 SECONDS AT 260°C.

TABLE:

ITEM	P/N	HOUSING COLOR	FUNCTIONAL AREA CONTACTS	SOLDER AREA CONTACTS	SHELL PLATING	包装要求
1	Z-CF007SLB02R-A-01	BLACK	Au:3u"	Sn	Ni	载带热封
2	Z-CF007SLB02L-A-01	BLACK	Au:3u"	Sn	Ni	载带冷封

东莞市溪榜电子有限公司

PART NAME	CONNECTOR			DRAWING	Y.C.ZHANG	DWG.No.	SBICL
PART NO.	USB C F TYPE母座直立式SMT短体CONN.			CHECK	G.C.Chen	REV.	A1
UNIT : mm	TOLERANCE OTHERWISE	UP TO 5 ±0.2 ABOVE 5 ~30 ±0.3 ABOVE 30 ±0.5 ANGLE ±3°	ANGLE 0°±3°	APPROVAL		DATE	
				SCALE	2:1	PAGE	1 OF 1

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